

### Nch 60V 3.5A Small Signal MOSFET

### Datasheet

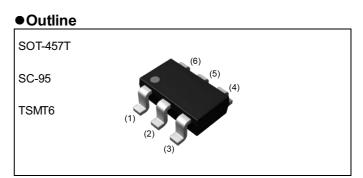
V <sub>DSS</sub>	60V
R <sub>DS(on)</sub> (Max.)	70mΩ
I <sub>D</sub>	±3.5A
P <sub>D</sub>	1.25W

### Features

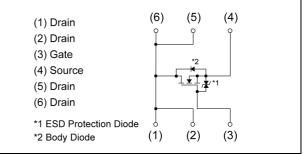
Application

Switching

- 1) Low on resistance
- 2) Built-in G-S protection diode
- 3) Small surface mount package(TSMT6)
- 4) Pb-free lead plating ; RoHS compliant
- 5) AEC-Q101 Qualified



#### ●Inner circuit



### Packaging specifications

Туре	Packing	Embossed Tape
	Reel size (mm)	180
	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TR
	Marking	PH

### • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	60	V
Continuous drain current	I <sub>D</sub>	±3.5	Α
Pulsed drain current	I <sub>DP</sub> *1	±14	A
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Dower discipation	P <sub>D</sub> *2	1.25	W
Power dissipation	P <sub>D</sub> *3	0.95	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

### •Thermal resistance

Deremeter	Sympol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres innetion embient	$R_{thJA}^{*2}$	-	-	100	°C/W
Thermal resistance, junction - ambient	$R_{thJA}^{*3}$	-	-	132	°C/W

### •Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Currence of	Conditions	Values		Unit		
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		60	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	63.7	-	mV/°C	
Zero gate voltage drain current			-	-	1	μA	
Gate - Source leakage current		$V_{GS}$ = ±20V, $V_{DS}$ = 0V	-	-	±10	μA	
Gate threshold voltage	$V_{GS(th)}$	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	1.0	-	3.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-4.4	-	mV/°C	
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.5A	-	50	70		
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.5A	-	58	82	mΩ	
		V <sub>GS</sub> = 4.0V, I <sub>D</sub> = 3.5A	-	62	87		
Gate resistance	R <sub>G</sub> f = 1MHz, open drain		-	8.1	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>   <sup>*4</sup>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 3.5A	3.0	-	-	S	

\*1 Pw $\leq$ 10µs , Duty cycle $\leq$ 1%

\*2 Mounted on a ceramic board (30×30×0.8mm)

- \*3 Mounted on a FR4 (25×25×0.8mm)
- \*4 Pulsed



# • Electrical characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Sumpleal	Conditions		Unit			
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub> V <sub>GS</sub> = 0V		-	430	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 10V	-	120	-	pF	
Reverse transfer capacitance	C <sub>rss</sub> f = 1MHz		-	55	-		
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq 30V, V_{GS}$ = 10V	-	18	-		
Rise time t <sub>r</sub> *4		I <sub>D</sub> = 1.75A	-	9	-	20	
Turn - off delay time	delay time t <sub>d(off)</sub> *4		-	35	-	ns	
Fall time	t <sub>f</sub> *4	R <sub>G</sub> = 10Ω	-	6	-		

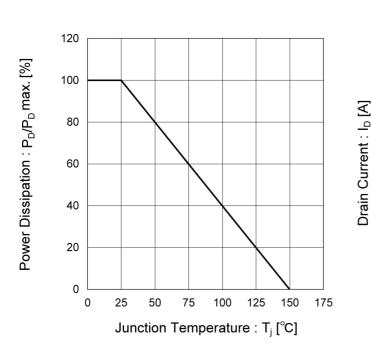
### • Gate charge characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q <sub>g</sub> *4	V <sub>DD</sub> ≃ 30V,	-	6.5	-	
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 3.5A,	-	2.0	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4	V <sub>GS</sub> = 5.0V	-	2.5	-	

# •Body diode electrical characteristics (Source-Drain) ( $T_a = 25^{\circ}C$ )

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ <sub>s</sub>	$T = 25^{\circ}$	-	-	1.6	А
Pulse forward current	$I_{SP}^{*1}$	T <sub>a</sub> = 25°C	-	-	14	А
Forward voltage	$V_{SD}^{*4}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = 3.5A	-	-	1.2	V





### Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

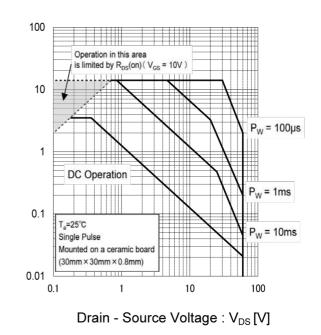
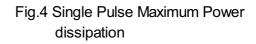
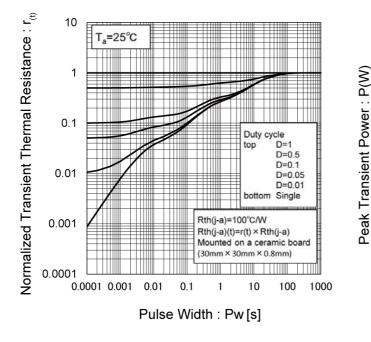


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width





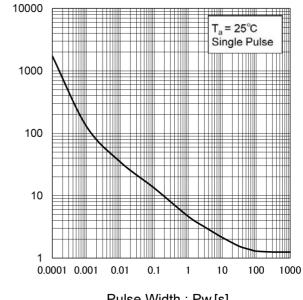
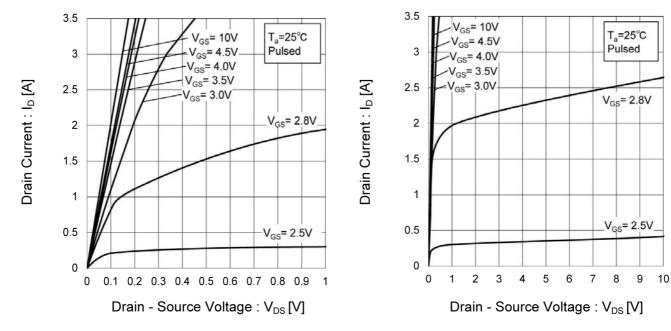


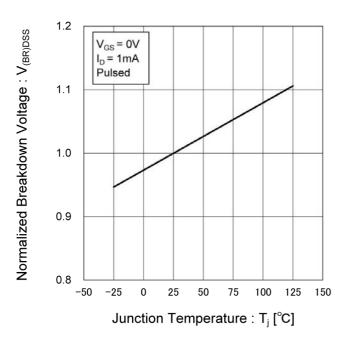


Fig.6 Typical Output Characteristics(II)



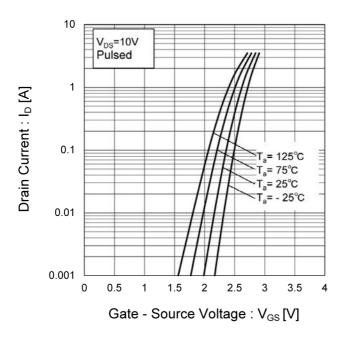
#### Fig.5 Typical Output Characteristics(I)

Fig.7 Breakdown Voltage vs. Junction Temperature



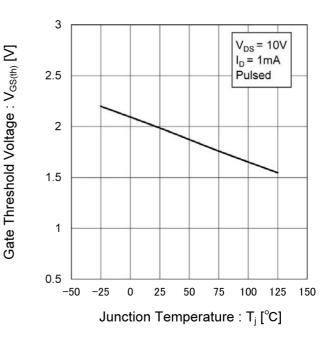




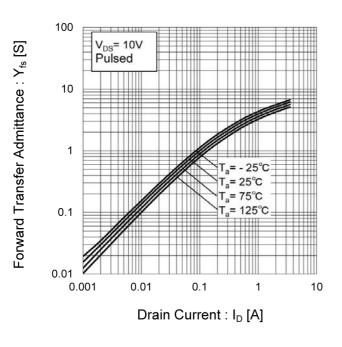


### Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature



### Fig.10 Forward Transfer Admittance vs. Drain Current





### • Electrical characteristic curves

Fig.11 Drain Current Derating Curve

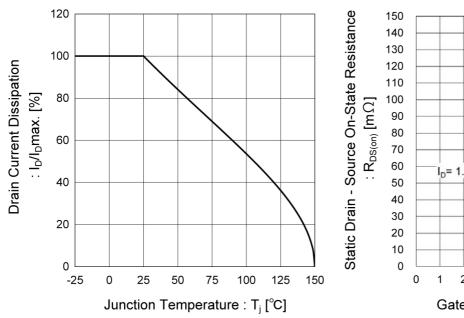


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

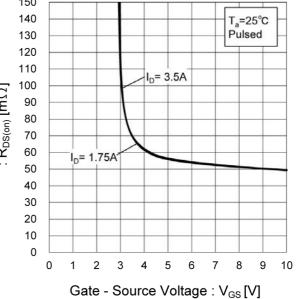
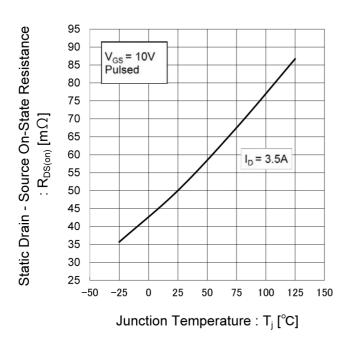


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





7/11



### • Electrical characteristic curves

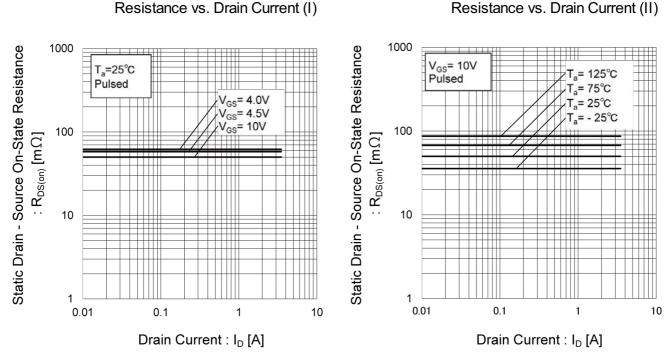


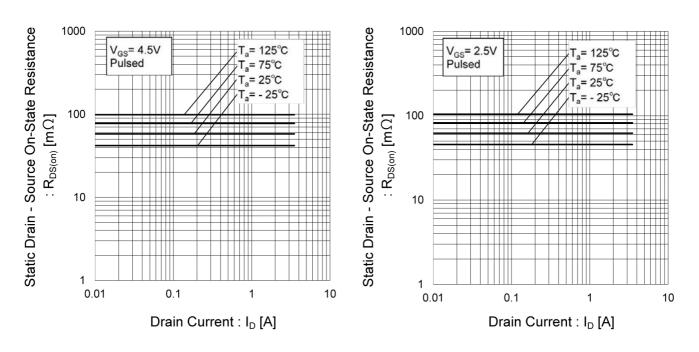
Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

Fig.16 Static Drain - Source On - State

Resistance vs. Drain Current (III)

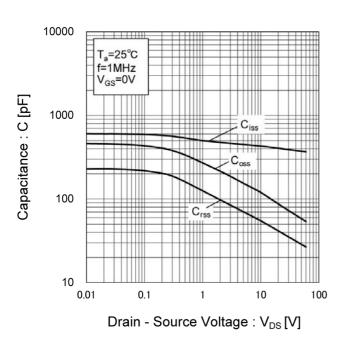
Fig.17 Static Drain - Source On - State Resistance vs. Drain Current (IV)

Fig.15 Static Drain - Source On - State





### • Electrical characteristic curves



### Fig.18 Typical Capacitance vs. Drain - Source Voltage

Fig.19 Switching Characteristics

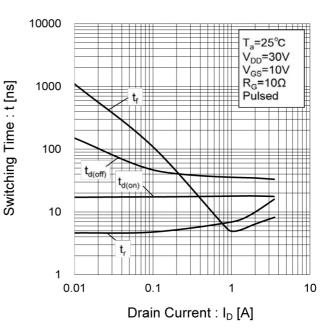


Fig.20 Dynamic Input Characteristics

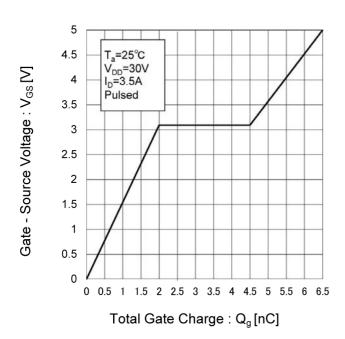
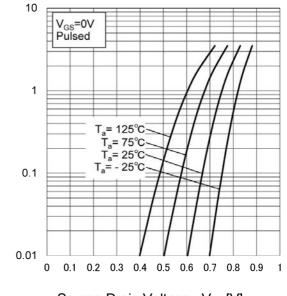


Fig.21 Source Current vs. Source Drain Voltage



Source-Drain Voltage :  $V_{\text{SD}}$  [V]

Source Current :I<sub>s</sub> [A]

#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

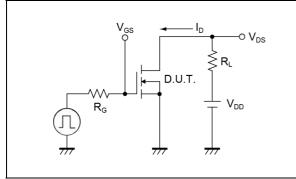


Fig.2-1 Gate Charge Measurement Circuit

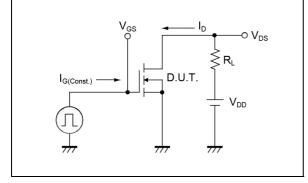
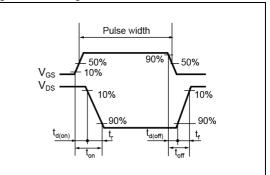
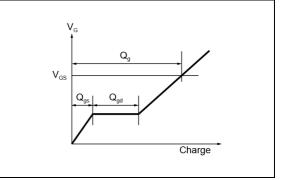


Fig.1-2 Switching Waveforms



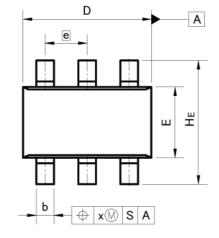


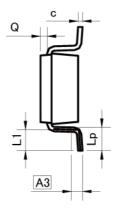


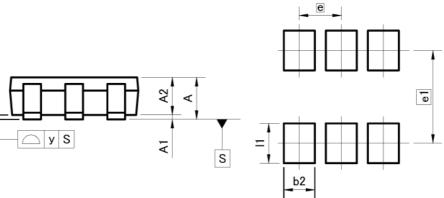


#### Dimensions









Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A	14	1.00	-	0.039
A1	0.00	0.10	0.000	0.004
A2	0.75	0.95	0.030	0.037
A3	0.	25	0.0	10
b	0.35	0.50	0.014	0.020
С	0.10	0.26	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.	95	0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.05	0.25	0.002	0.010
x		0.20	-	0.008
у	÷	0.10		0.004
	MILIM	ETERS	INC	HES
DIM -	MIN	MAX	MIN	MAX
b2	]	0.70	-	0.028
e1	2.	10	0.0	83
	1000			

Dimension in mm/inches

-

11



0.90

-



0.035

# Notice

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(Note1) Medical Equipment Classification of the Specific Ap	oplications
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JAPAN	USA	EU	CHINA
CLASSII	CLASSⅢ	CLASS II b	CLASSII
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  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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